

Appl. No. : 10/803,272
Filed : March 18, 2004

AMENDMENTS TO THE SPECIFICATION

In the changes made to the specification by the current amendment, deletions are shown by strikethrough (e.g., ~~deletion~~), and additions are underlined (e.g., addition).

On page 1 of the Specification, in Paragraph [0002], please revise the existing paragraph as follows:

Related Applications

[0002] This application is related to U.S. Patent Application Nos. ^(Patent No. 7,038,166) 10/690,833, ^(Patent No. 7,057,134) 10/690,975, 10/691,481, and 10/691,444, each of which were filed on October 22, 2003 and each of which is incorporated in its entirety by reference herein. This application is also related to U.S. Patent Applications Nos. ^(Patent No. 7,038,164) 10/803,243 ~~(Attorney Docket No. LOMASR-023CP1)~~ and 10/803,267 ~~(Attorney Docket No. LOMASR-026CP1)~~, both of which were filed on March 18, 2004, ~~even date herewith~~ and both of which are incorporated in their entireties by reference herein.

METHOD AND APPARATUS FOR MATERIAL PROCESSINGClaim of Priority

[0001] This application is a continuation-in-part from U.S. Patent Application No. 10/690,983, filed October 22, 2003, ^(Patent No. 7,060,932 B2) which claims benefit under 35 U.S.C. § 119(e) to U.S. Provisional Patent Application No. 60/456,043, filed March 18, 2003, to U.S. Provisional Patent Application No. 60/471,057, filed May 16, 2003, and to U.S. Provisional Patent Application No. 60/496,460, filed August 20, 2003, each of which is incorporated in its entirety by reference herein.

Related Applications

[0002] This application is related to U.S. Patent Application Nos. 10/690,833, 10/690,975, 10/691,481, and 10/691,444, each of which were filed on October 22, 2003 and each of which is incorporated in its entirety by reference herein. This application is also related to U.S. Patent Applications Nos. _____ (Attorney Docket No. LOMASR.023CPI) and _____ (Attorney Docket No. LOMASR.026CPI), both of which are filed on even date herewith and are incorporated in their entireties by reference herein.

Statement Regarding Federally Sponsored Research or Development

[0003] This invention was funded, in part, by the Federal Emergency Management Agency as part of the Robert T. Stafford Disaster Relief and Emergency Assistance Act (42 U.S.C. § 5121 *et seq.*).

Background of the InventionField of the Invention

[0004] The present invention relates to the field of material processing, particularly, to an apparatus and method for drilling, cutting, and surface processing of materials using energy waves.

Description of the Related Art

[0005] Those in the wide ranging materials processing industries have long recognized the need for non-disruptive material processing. In the past, virtually all material processing, including drilling, cutting, scabbling, and the like have included numerous disruptive aspects (e.g., noise, vibration, dust, vapors, and fumes). Material processing